

**STRUCTURE** Silicon Monolithic Integrated Circuit  
**TYPE** 1A Low Dropout Voltage Regulator(Adjustable Voltage)  
**PRODUCT SERIES** **BAXXCCOFP Series**  
**FEATURES** Maximum Output Current : 1A  
 High Input Voltage : 35V, Built in Over Voltage Protection

○ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

Parameter	Symbol	Limits	Unit
Supply Voltage	Vcc	-0.3 ~ 35 ※1	V
Power Dissipation (TO252-5)	Pd	1200 ※2	mW
Operating Temperature Range	Topr	-40~+125	°C
Storage Temperature Range	Tstg	-55~+150	°C
Junction Temperature	Tjmax	150	°C
Peak Supply Voltage	Vcc peak	50 ※3	V

※1 Do not however exceed Pd.

※2 Derating in done at 9.6mW/°C for operating above Ta≥25°C.

※3 Bias voltage in 200msec (tr≥1msec). See NOTES FOR USE No.6.

○RECOMMENDED OPERATING CONDITIONS (Ta=-40~125°C, however do not exceed Pd.)

Parameter	Symbol	Min.	Max.	Unit
Supply Voltage	Vcc	4.0	25.0	V
Output Current	Io	—	1.0	A

○PROTECTION (Design Guarantee)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Over Voltage Protection	Vcc	26	28	30	V

NOTE The product described in this specification is a strategic product (and/or service) subject to COCOM regulations. It should not be exported without authorization from the appropriate government.

NOTE This product is not designed for normal operation within a radio active environment.

Status of this document

The Japanese version of this document is the formal specification.

A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.

○ELECTRICAL CHARACTERISTIC (Unless otherwise specified, Ta=25°C、Vctl=5V、Io=500mA) ※1

Parameter	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Output Voltage ※2	Vo	Vo(T) × 0.98	Vo(T)	Vo(T) × 1.02	V	
Bias Current	Ib	—	2.5	5.0	mA	VCTL=2V, Io=0mA
Dropout Voltage	ΔVd	—	0.3	0.5	V	Vcc=Vo(T) × 0.95
Peak Output Current	Io	1.0	—	—	A	
Ripple Rejection	R.R.	45	55	—	dB	f=120Hz, Io=100mA, ein※4=1Vrms
Line Regulation	Reg.I	—	20	100	mV	Vcc=Vo(T)+1→25V
Load Regulation	Reg.L	—	50	150	mV	Io=5mA→1A
Temperature Coefficient of Output Current ※3	Tcvo	—	±0.02	—	%/°C	Io=5mA, Tj=0~125°C
Output Short Current	Ios	—	0.40	—	A	Vcc=25V

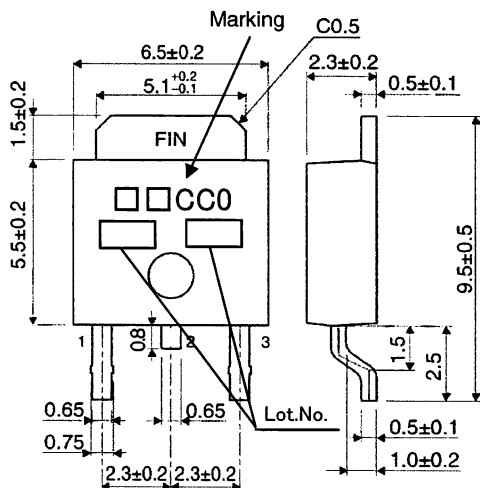
※1 Vo=3.0V:Vcc=8V, Vo=3.3V:Vcc=8.3V, Vo=5V:Vcc=10V, Vo=6V:Vcc=11V, Vo=7V:Vcc=12V, Vo=8V:Vcc=13V, Vo=9V:Vcc=14V, Vo=10V:Vcc=15V, Vo=12V:Vcc=17V, Vo=15V:Vcc=20V

※2 Vo(T)=3.3, 5.0, 6.0, 7.0, 8.0, 9.0, 12.0V

※3 Design guarantee.(Outgoing inspection is not done on all products.)

※4 ein : Input Voltage Ripple

○PHYSICAL DIMENSIONS, MARKING

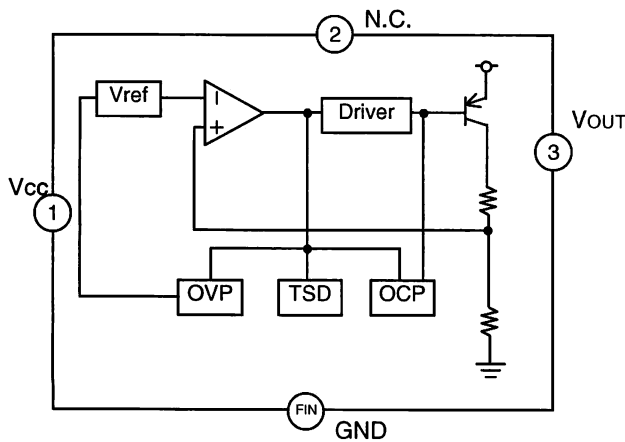


TO252-3 (UNIT : mm)

○MARKING, OUTPUT VOLTAGE

Parts Number	Marking	Output Voltage (V)	Parts Number	Marking	Output Voltage (V)
BA03CC0FP	03CC0	3.0	BA08CC0FP	08CC0	8.0
BA033CC0FP	033CC0	3.3	BA09CC0FP	09CC0	9.0
BA05CC0FP	05CC0	5.0	BAJ0CC0FP	J0CC0	10.0
BA06CC0FP	06CC0	6.0	BAJ2CC0FP	J2CC0	12.0
BA07CC0FP	07CC0	7.0	BAJ5CC0FP	J5CC0	15.0

BLOCK DIAGRAM



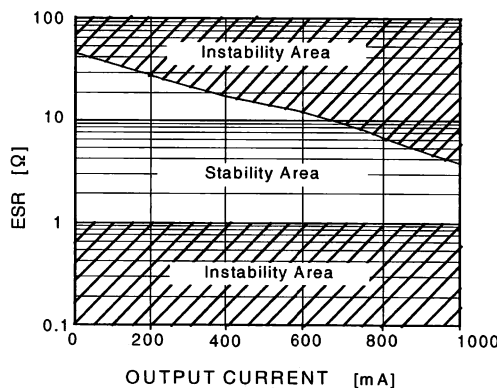
OPIN NO. , PIN NAME

Pin Number	Pin Name
1	Vcc
2	N.C.
3	VOUT
FIN	GND

※ Please refer to technical note concerning application circuit, and etc.

ONOTES FOR USE

- 1. Absolute maximum range**  
 Absolute Maximum Ratings are those values beyond which the life of a device may be destroyed we cannot be defined the failure mode, such as short mode or open mode.  
 Therefore physical security countermeasure, like fuse, is to be given when a specific mode to be beyond absolute maximum ratings is considered.
- 2. GND pin voltage**  
 GND terminal should be connected the lowest voltage, under all conditions. And all terminals except GND should be under GND terminal voltage under all conditions including transient situations.
- 3. Power dissipation**  
 If IC is used on condition that the power loss is over the power dissipation, the reliability will become worse by heat up, such as reduced output current capability.  
 Also, be sure to use this IC within a power dissipation range allowing enough of margin.
- 4. Electrical characteristics described in these specifications may vary, depending on temperature, supply voltage, external circuits and other conditions. Therefore, be sure to check all relevant factors, including transient characteristics.**
- 5. Be sure to connect a capacitor with capacitance of at least 22μF, including temperature characteristics and variation, to prevent oscillation between the Vo and GND. Note that if the capacity of the capacitor changes due to factors such as changes in temperature or ESR, oscillation may occur, and the original characteristics of the IC may not be realized. For example, when a ceramic capacitor is employed, oscillation will be generated because the series resistance is too small. Please take countermeasures to prevent this, such as adding a series resistor. Standard electrolytic capacitors are subject to extremely large capacitance and ESR fluctuations due to temperature conditions. Particularly at low temperature, capacity is decreased, while ESR grows larger, conditions which increase the vulnerability to oscillation. Therefore, be certain to check for the presence of oscillation.**  
 In respect to the proper ESR range, select a capacitor that meets the conditions in the figure below for stable operation range. Note, however, that the stable range suggested in the figure depends on the IC and the resistance load involved, and can vary with the board's wiring impedance, input impedance, and/or load impedance. Therefore, be certain to ascertain the final status of these items for actual use.  
 Keep capacitor capacitance within a range of 22μF~1000μF. It is also recommended that a 0.33μF bypass capacitor be connected as close to the input pin-GND as location possible. However, in situations such as rapid fluctuation of the input voltage or the load, please check the operation in real application to determine proper capacitance.



6. Over voltage protection circuit

The over voltage protection is useful for the sharp surge voltage.

(Rise Time: more than 1msec)

If the surge voltage is supplied for a longer time, another protection circuit (ex. power zenner) should be added.

7. Overcurrent protection circuit

The built-in overcurrent protection circuit is designed to respond to the output current and prevent destruction of the IC from load short circuits; however, it is only effective in protecting the IC from destruction in sudden overcurrent accidents. The protection circuit is not to be used continuously, or for transitions. In executing thermal design, bear in mind that overcurrent protection has negative characteristic according with the temperature.

8. Thermal shutdown circuit

A built-in internal shutdown (TSD) circuit is provided to protect the IC from heat destruction. Operation has to be done within the allowable loss range, but in continuous use beyond the range, chip temperature  $T_j$  will increase to the threshold, activating the TSD circuit and turning the output power Tr OFF. Once the chip temperature  $T_j$  returns to the normal range, the circuit is automatically restored. Note that the TSD circuit is designed to operate over the maximum absolute rating. Therefore, make absolutely certain not to use the TSD function in set design.

9. Mounting Failures

Mounting failure, such as misdirection or mismount, may cause a malfunction in the device.

10. Internal circuits or elements may be damaged when Vcc and pin voltage are reversed. For example, Vcc short circuit to GND while a external capacitor is charged. Output pin capacitor is recommended no larger than 1000 $\mu$ F. In addition, inserting a Vcc series countercurrent prevention diode, or a bypass diode between the various pins and the vcc, is recommended.

11. Malfunction may be happened when the device is used in the strong electromagnetic field.

12. We recommend to put Diode for protection purpose in case of output pin connected with large load of impedance or reserve current occurred at initial and output off.

13. Precautions for board inspection

Connecting low-impedance capacitors to run inspections with the board may produce stress on the IC. Therefore, be certain to use proper discharge procedure before each process of the test operation. To prevent electrostatic accumulation and discharge in the assembly process, thoroughly ground yourself and any equipment that could sustain ESD damage, and continue observing ESD-prevention procedures in all handling, transfer and storage operations. Before attempting to connect components to the test setup, make certain that the power supply is OFF. Likewise, be sure the power supply is OFF before removing any component connected to the test setup.

14. GND pattern

When both a small-signal GND and high current GND are present, single-point grounding (at the set standard point) is recommended, in order to separate the small-signal and high current patterns, and to be sure the voltage change stemming from the wiring resistance and high current does not cause any voltage change in the small-signal GND. In the same way, care must be taken to avoid voltage fluctuations in any connected external component GND.

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